Agilent Technologies

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EMPro Default 3D Library

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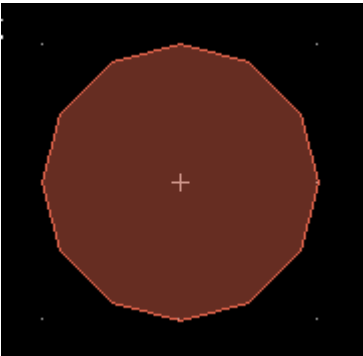
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EMPro_LIBS3D_Block

Description: A block

Library: EMPro Default 3D Library

Parameters

Name	Description	Default Value	Unit
Desc3D	An XML file containing the model data.	None	None
DesignKitName	The design kit containing the component.	None	None
Layer	The layer for placing a block.	cond:drawing	None
Layer2	The layer used to draw the markup.	default:drawing	None
PlaceCustomComponentOnTop	Place the component on top of the specified layer.	None	None
depth	Depth of block	1.00e+001	mil
height	Height of block	1.00e+001	mil
material	Material	Cu	None
width	Width of block	1.00e+001	mil

EMPro_LIBS3D_BlockArray
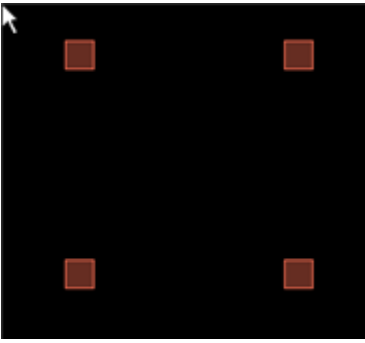
Description: An array of blocks

Library: EMPro 3D library

Parameters

Name	Description	Default Value	Unit
Desc3D	XML file containing the model data	None	None
DesignKitName	The Design Kit containing the component	None	None
Layer	The layer on which to place the block.	cond:drawing	None
Layer2	The layer used to draw the markup.	default:drawing	None
PlaceCustomComponentOnTop	Place the component on top of the specified layer.	No	None
depth	Depth of block	1.00e+001	mil
dx	Distance between components in X direction	8e+001	mil
dy	Distance between components in Y direction	8e+001	mil
height	Height of block	0.000254	meter
material	Material	Cu	None
nx	Number of components in X direction	2	None
ny	Number of components in Y direction	2	None
width	Width of block	1.00e+001	mil

EMPro_LIBS3D_BlockArrayOutline
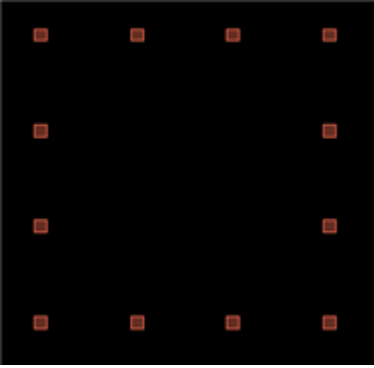
Description: An outline of an array of blocks

Library:

Parameters

Name	Description	Default Value	Unit
Desc3D	XML file containing the model data		
DesignKitName	The Design Kit containing the component		
Layer	The layer on which to place the block.	cond:drawing	
Layer2	The layer used to draw the markup.	default:drawing	
PlaceCustomComponentOnTop	Place the component on top of the specified layer.	No	
depth	Depth of block	1.00e+001	mil
dx	Distance between components in X direction	8e+001	mil
dy	Distance between components in Y direction	8e+001	mil
height	Height of block	1.00e+001	mil
material	Material	Cu	None
nx	Number of components in X direction	4	None
ny	Number of components in Y direction	4	None
width	Width of block	1.00e+001	mil

EMPro_LIBS3D_Cylinder

Description: A cylinder

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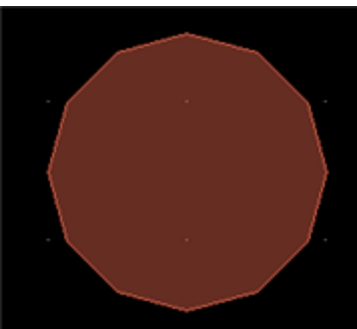
Description: A cylinder

Library: EMPro 3D library

Parameters

Name	Description	Default Value	Unit
Desc3D	XML file containing the model data		
DesignKitName	The Design Kit containing the component		
Layer	The layer on which to place the block.	cond:drawing	
Layer2	The layer used to draw the markup.	default:drawing	
PlaceCustomComponentOnTop	Place the component on top of the specified layer.	No	
division	Number of divisions along z	12	None
height	Height of cylinder	1.00e+001	mil
material	Material	Cu	
radius	Radius of cylinder	1.00e+001	mil

EMPro_LIBS3D_CylinderArray
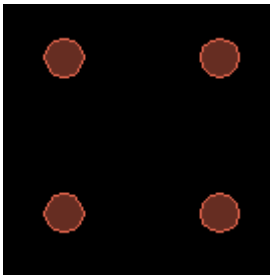
Description: An array of Cylinders

Library: EMPro 3D Library

Parameters

Name	Description	Default Value	Unit
Desc3D	XML file containing the model data		
DesignKitName	The Design Kit containing the component		
Layer	The layer on which to place the cylinder	cond:drawing	
Layer2	The layer used to draw the markup.	default:drawing	
PlaceCustomComponentOnTop	Place the component on top of the specified layer.	No	
arcResolution	Arc resolution for the circular cross-section of the solder ball	45	deg
divisions	Number of divisions along z	12	none
dx	Distance between components in X direction	8e+001	mil
dy	Distance between components in Y direction	8e+001	mil
height	Height of solder ball	1.00e+001	mil
material	Material	Cu	
radius	radius of cylinder	1.00e+001	mil
nx	Number of components in X direction	2	None
ny	Number of components in Y direction	2	None

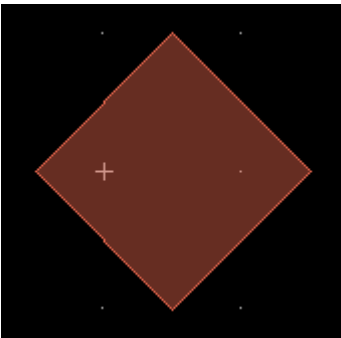# EMPro_LIBS3D_CylinderArrayOutline
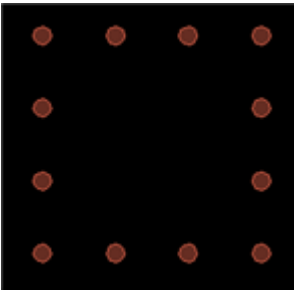
Description: An outline of an array of Cylinders

Library: EMPro 3D Library

Parameters

Name	Description	Default Value	Unit
Desc3D	XML file containing the model data	None	None
DesignKitName	The Design Kit containing the component	None	None
Layer	The layer on which to place the cylinder	cond:drawing	None
Layer2	The layer used to draw the markup.	default:drawing	None
PlaceCustomComponentOnTop	Place the component on top of the specified layer.	No	None
divisions	Number of divisions along z	12	None
dx	Distance between components in X direction	8e+001	mil
dy	Distance between components in Y direction	8e+001	mil
height	Height of cylinder	1.00e+001	mil
material	Material	Cu	None
nx	Number of components in X direction	4	None
ny	Number of components in Y direction	4	None
radius	Radius of cylinder	1.00e+001	mil

EMPro_LIBS3D_SolderBall

Description: A solder ball

Library: EMPro 3D Library

Parameters

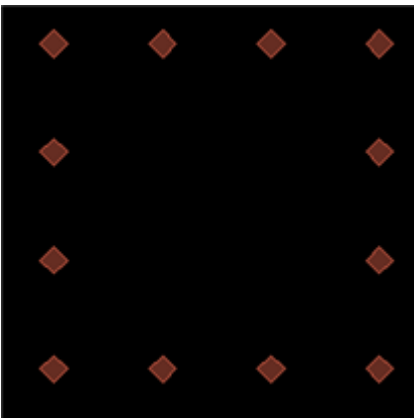| Name	Description	Default Value	Unit
Desc3D	XML file containing the model data	None	None
DesignKitName	The Design Kit containing the component	None	None
Layer	The layer on which to place the solder ball	cond:drawing	None
Layer2	The layer used to draw the markup	default:drawing	None
PlaceCustomComponentOnTop	Place the component on top of the specified layer	No	None
arcResolution	Arc resolution for the circular cross-section of the solder ball	45	deg
divisions	Number of divisions along z	3	None
height	Height of solder ball	1.00e+001	mil
material	Material	Cu	None
maxRadius	Maximal radius of solder ball	1.25e+001	mil
minRadius	Minimal radius of solder ball	1.00e+001	mil

EMPro_LIBS3D_SolderBallArray

Description: An array of solder balls

Library: EMPro 3D Library

Parameters

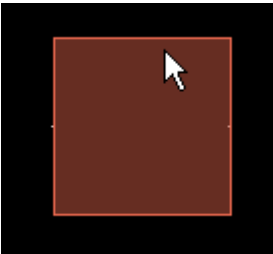| Name	Description	Default Value	Unit
Desc3D	XML file containing the model data	None	None
DesignKitName	The Design Kit containing the component	None	None
Layer	The layer on which to place the solder ball.	cond:drawing	None
Layer2	The layer used to draw the markup.	default:drawing	None
PlaceCustomComponentOnTop	Place the component on top of the specified layer.	No	None
arcResolution	Arc resolution for the circular cross-section of the solder ball	45	deg
divisions	Number of divisions along z	3	None
dx	Distance between components in X direction	8e+001	mil
dy	Distance between components in Y direction	8e+001	mil
height	Height of solder ball	1.00e+001	mil
material	Material	Cu	None
maxRadius	Maximal radius of solder ball	1.25e+001	mil
minRadius	Minimal radius of solder ball	1.00e+001	mil
nx	Number of components in X direction	2	None
ny	Number of components in Y direction	2	None

EMPro_LIBS3D_SolderBallArrayOutline

Description: An outline of an array of solder balls

Library: EMPro 3D Library

Parameters

Name	Description	Default Value	Unit
Desc3D	XML file containing the model data	None	None
DesignKitName	The Design Kit containing the component	None	None
Layer	The layer on which to place the solder ball.	cond:drawing	None
Layer2	The layer used to draw the markup	default:drawing	None
PlaceCustomComponentOnTop	Place the component on top of the specified layer	No	
arcResolution	Arc resolution for the circular cross-section of the solder ball	45	deg
divisions	Number of divisions along z	3	none
dx	Distance between components in X direction	8e+001	mil
dy	Distance between components in Y direction	8e+001	mil
height	Height of solder ball	1.00e+001	mil
material	Material	Cu	None
maxRadius	Maximal radius of solder ball	1.25e+001	mil
minRadius	Minimal radius of solder ball	1.00+001	mil
nx	Number of components in X direction	4	None

EMPro_LIBS3D_SpanBlock

Description:A block spanning over a layer

Library: EMPro 3D Library

Parameters

Name	Description	Default Value	Unit
Desc3D	XML file containing the model data	None	None
DesignKitName	The Design Kit containing the component	None	None
Layer	The layer over which the cylinder will span	cond:drawing	None
Layer2	The layer used to draw the markup.	default:drawing	None
depth	Depth of block	1.00e+001	mil
material	Material	Cu	None
width	Width of block	1.00e+001	mil

EMPro_LIBS3D_SpanBlockArray
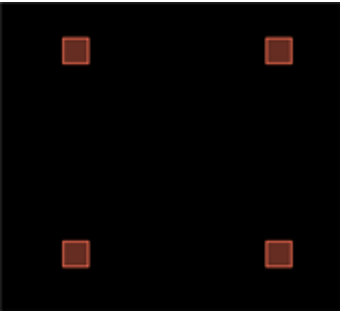
Description: An array of SpanBlocks

Library: EMPro 3D Library

Parameters

Name	Description	Default Value	Unit
Desc3D	XML file containing the model data		
DesignKitName	The Design Kit containing the component		
Layer	The layer over which the block will span	cond:drawing	
depth	Depth of block	1.00e+001	mil
Layer2	The layer used to draw the markup.	default:drawing	
dx	Distance between components in X direction	8e+001	mil
dy	Distance between components in Y direction	8e+001	mil
height	Height of solder ball	0.000254	meter
material	Material	Cu	
nx	Number of components in X direction	2	None
ny	Number of components in Y direction	2	None
width	Width of block	1.00e+001	mil

EMPro_LIBS3D_SpanBlockArrayOutline

Description: An outline of an array of SpanBlocks

Library: EMPro 3D Library

Parameters

Name	Description	Default Value	Unit
Desc3D	XML file containing the model data		
DesignKitName	The Design Kit containing the component		
Layer	The layer over which the block will span	cond:drawing	
Layer2	The layer used to draw the markup.	default:drawing	
depth : Depth of block	1.00e+001		mil
dx	Distance between components in X direction	8e+001	mil
dy	Distance between components in Y direction	8e+001	mil
material	Material	Cu	
nx	Number of components in X direction	2	None
ny	Number of components in Y direction	2	None
width : Width of block	1.00e+001		mil

EMPro_LIBS3D_SpanCylinder

Description: A cylinder spanning over a layer

Library: EMPro 3D Library

Parameters

Name	Description	Default Value	Unit
Desc3D	XML file containing the model data	None	None
DesignKitName	The Design Kit containing the component	None	None
Layer	The layer over which the cylinder will span	cond:drawing	None
Layer2	The layer used to draw the markup	default:drawing	None
divisions	Number of divisions along z	12	None
material	Material	Cu	None
radius	Radius of cylinder	1.00e+001	mil

EMPro_LIBS3D_SpanCylinderArray
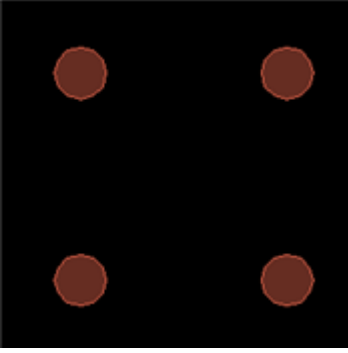
Description: An array of Span Cylinders

Library: EMPro 3D Library

Parameters

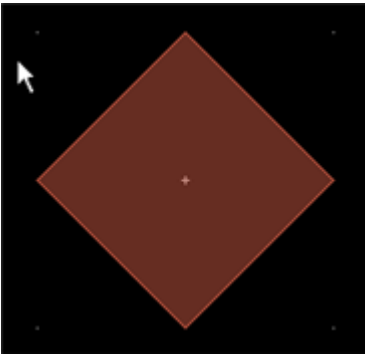| Name	Description	Default Value	Unit
Desc3D	XML file containing the model data	None	None
DesignKitName	The Design Kit containing the component	None	None
Layer	The layer over which the cylinder will span	cond:drawing	None
Layer2	The layer used to draw the markup.	default:drawing	None
divisions	Number of divisions along z	12	None
dx	Distance between components in X direction	8e+001	mil
dy	Distance between components in Y direction	8e+001	mil
material	Material	Cu	None
nx	Number of components in X direction	2	none
ny	Number of components in Y direction	2	None
radius	Radius of cylinder	1.00e+001	mil

EMPro_LIBS3D_SpanCylinderArrayOutline
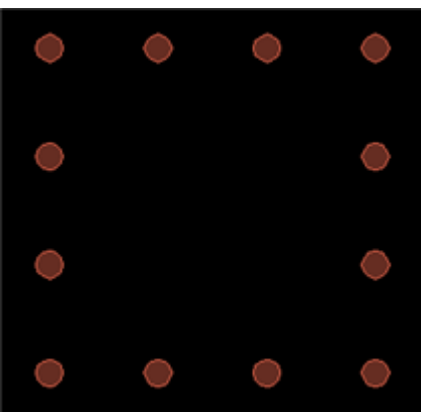
Description: An outline of an array of span cyclinders

Library: EMPro 3D Library

Parameters

Name	Description	Default Value	Unit
Desc3D	XML file containing the model data		
DesignKitName	The Design Kit containing the component		
Layer	The layer on over which the cylinder will span	cond:drawing	
Layer2	The layer used to draw the markup.	default:drawing	
PlaceCustomComponentOnTop	Place the component on top of the specified layer.	No	
division	Number of divisions along z	12	None
dx	Distance between components in X direction	8e+001	mil
dy	Distance between components in Y direction	8e+001	mil
material	Material	Cu	
nx	Number of components in X direction	4	None
ny	Number of components in Y direction	4	None
radius	Radius of cylinder	1.00e+001	mil

EMPro_LIBS3D_SpanSolderBall

Description: A solder ball spanning over a layer

Library: EMPro 3D Library

Parameters

Name	Description	Default Value	Unit
Desc3D	XML file containing the model data	None	None
DesignKitName	The Design Kit containing the component	None	None
Layer	The layer over which the solder ball will span.	cond:drawing	None
Layer2	The layer used to draw the markup.	default:drawing	None
arcResolution	Arc resolution for the circular cross-section of the solder ball	45	deg
divisions	Number of divisions along z	3	None
material	Material	Cu	None
maxRadius	Maximal radius of solder ball	1.25e+001	mil
minRadius	Minimal radius of solder ball	1.00e+001	mil

EMPro_LIBS3D_SpanSolderBallArray

Description:An array of spanning solder balls

Library: EMPro 3D Library

Parameters

Name	Description	Default Value	Unit
Desc3D	XML file containing the model data		
DesignKitName	The Design Kit containing the component		
Layer	The layer over which the solder ball will span	cond:drawing	
Layer2	The layer used to draw the markup.	default:drawing	
arcResolution	Arc resolution for the circular cross-section of the solder ball	45	deg
divisions	Number of divisions along z	3	none
dx	Distance between components in X direction	8e+001	mil
dy	Distance between components in Y direction	8e+001	mil
material	Material	Cu	
maxRadius	Maximal radius of solder ball	1.25e+001	mil
minRadius	Minimal radius of solder ball	1.00e+001	mil
nx	Number of components in X direction	2	None
ny	Number of components in Y direction	2	None

EMPro_LIBS3D_SpanSolderBallArrayOutline

Description: An outline of an array of spanning solder balls

Library: EMPro 3D Library

Parameters

Name	Description	Default Value	Unit
Desc3D	XML file containing the model data		
DesignKitName	The Design Kit containing the component		
Layer	The layer over which the solder ball will span	cond:drawing	
Layer2	The layer used to draw the markup.	default:drawing	
arcResolution	Arc resolution for the circular cross-section of the solder ball	45	deg
divisions	Number of divisions along z	3	none
dx	Distance between components in X direction	8e+001	mil
dy	Distance between components in Y direction	8e+001	mil
material	Material	Cu	
maxRadius	Maximal radius of solder ball	1.25e+001	mil
minRadius	Minimal radius of solder ball	1.25e+001	mil
nx	Number of components in X direction	4	None
ny	Number of components in Y direction	4	None